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Page 1 of 1

APPLICANT:
Kazushi Higashi et al.FILING DATE:
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U.S. PATENT DOCUMENTS

Examiner Initial		Document No.	Date	Name	Class	Subclass	Filing Date
	A						
	B						
	C						
	D						
	E						
	F						
	G						
	H						

FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Class	Subclass	Translation
cy	I	3-241755	10/1991	JP			Eng. abstract & Partial Trans. Attached
	J						

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

cy	K	"Development of chip-on-chip bonding process at a room temperature (with copper, a bumpless bonding is also possible)", Semiconductor Sangyo Newspaper, June 12, 2002, pg. 9, Sangyo Times Inc., Tokyo, Japan.					
cy	L	"Development of chip-on-chip bonding process at a room temperature by a superbonder", Electronic Materials, July 1, 2002, pp. 8-9, Vol. 41 No. 7, Kogyo Chosakai Publishing Co., Ltd., Tokyo, Japan.					
cy	M	"Ultrasonic Flip Chip Bonding Technology for LSI Chip with High Pin Counts" by Kajiwaru et al., from Proceedings of the 7th Symposium on Microjoining and Assembly Technology in Electronics, February 1, 2001, pp. 16166, Japan Welding Society, Tokyo, Japan.					
	N						

Examiner

C. J. Ashe

Date Considered

6/10/05

*Examiner: Initial if reference considered, regardless of whether citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.